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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	75
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 20x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2138asnfp-v0

Table 1.2 Specifications (2)

Item	Function	Description
Serial interface	UART0_0 and UART0_1	2 channels Clock synchronous serial I/O mode, clock asynchronous serial I/O mode
	UART2	1 channel Clock synchronous serial I/O mode, clock asynchronous serial I/O mode, I^2C mode (I^2C-bus), multiprocessor communication mode
Clock Synchronous serial interface	(SSU) SSU_0	1 channel (also used for the I^2C bus)
	(I^2C bus) I^2C_0	1 channel (also used for the SSU)
LIN module	HW-LIN_0	Hardware LIN 1 channel (timer RJ_0, UART0_0, or UART0_1 used)
A/D converter		Resolution: 10 bits × 20 channels, sample and hold function, sweep mode
Comparator B		2 circuits
Touch sensor control unit (TSCU)		System CH × 4, electrostatic capacitive touch detection × 36
CRC calculator		CRC-CCITT ($X^{16} + X^{12} + X^5 + 1$), CRC-16 ($X^{16} + X^{15} + X^2 + 1$) compliant
Flash memory		• Program/erase voltage: VCC = 2.7 V to 5.5 V • Program/erase endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function • BGO (background operation) function (data flash)
Operating frequency/ Power supply voltage		CPU clock = 20 MHz (VCC = 2.7 V to 5.5 V) CPU clock = 5 MHz (VCC = 1.8 V to 5.5 V)
Current consumption		Typ. 6.5 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 4.0 μA (VCC = 3.0 V, wait mode f(XCIN) = 32 kHz) Typ. 2.2 μA (VCC = 3.0 V, stop mode)
Operating ambient temperature		-20°C to 85°C (N version) -40°C to 85°C (D version) (1)
Package		80-pin LQFP Package code: PLQP0080KB-A (previous code: 80P6Q-A)

Note:
1. Specify the D version if it is to be used.

Table 1.7 Pin Name Information by Pin Number (SSU/I²C, Timer RJ, and Timer RB2) (2)

Port	Pin No.	SSU/I²C						Timer RJ		Timer RB2
		SCL_0	SDA_0	SSI_0	$\overline{SCS\_0}$	SSCK_0	SSO_0	TRJO_0	TRJIO_0	TRBO_0
P8_0	44									
P8_1	43									
P8_2	42									
P8_3	41									
P8_4	40									
P8_5	39									
P8_6	38									
P8_7	37									
P9_0	34									
P9_1	33									
P9_2	32									
P9_3	31									
P9_4	79									
P9_5	78									

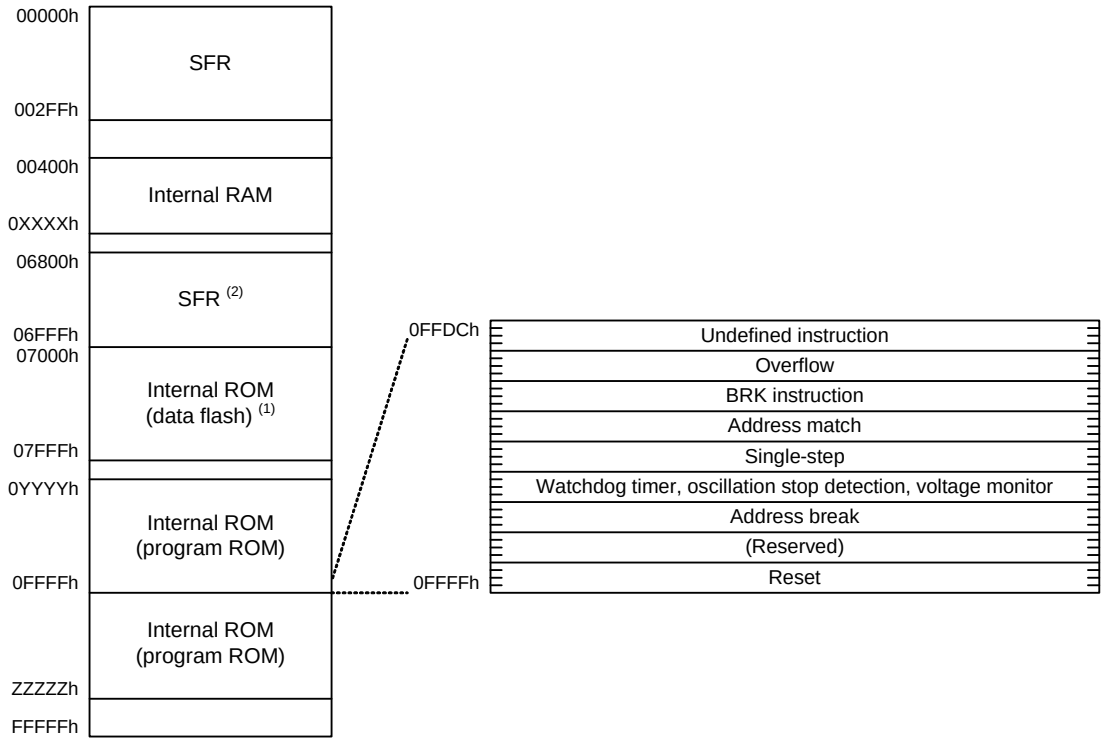
Table 1.11 Pin Functions (2)

Item	Pin Name	I/O	Description
A/D converter	AN0 to AN19	I	Analog input for the A/D converter.
	$\overline{\text{ADTRG}}$	I	External trigger input for the A/D converter.
Comparator B	IVCMP1, IVCMP3	I	Analog voltage input for comparator B.
	IVREF1, IVREF3	I	Reference voltage input for comparator B.
Touch sensor control unit	CHxA0, CHxA1, CHxB, CHxC	I/O	Control pins for electrostatic capacitive touch detection.
	CH00 to CH35	I	Electrostatic capacitive touch detection pins.
I/O ports	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_3 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_5	I/O	8-bit CMOS input/output ports. Each port has an I/O select direction register, enabling switching input and output for each pin. For input ports, the presence or absence of a pull-up resistor can be selected by a program. All ports can be used as LED drive (high drive) ports.
Input port	P4_2	I	Input-only port.

3. Address Space

3.1 Memory Map

Figure 3.1 shows the Memory Map. The R8C/38T-A Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. Up to 32 Kbytes of the internal ROM (program ROM) is allocated at lower addresses, beginning with address 0FFFFh. The area in excess of 32 Kbytes is allocated at higher addresses, beginning with address 10000h. For example, a 64-Kbyte internal ROM is allocated at addresses 08000h to 17FFFh.
The fixed interrupt vector table is allocated at addresses 0FFDCh to 0FFFFh. The start address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated at addresses 07000h to 07FFFh.
The internal RAM is allocated at higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM is allocated at addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated at addresses 00000h to 02FFFh and addresses 06800h to 06FFFh. Peripheral function control registers are allocated here. All unallocated locations within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Addresses 06800h to 06FFFh are used for the ELC, DTC, and TSCU SFR areas.
3. The blank areas are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F21388SNFP, R5F21388SDFP	64 Kbytes	08000h	17FFFh	6 Kbytes	01BFFh
R5F21388SNFP, R5F21388SDFP	96 Kbytes	08000h	1FFFFh	8 Kbytes	023FFh
R5F21388SNFP, R5F21388SDFP	128 Kbytes	08000h	27FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

Table 3.3 SFR Information (3) (1)

Address	Symbol	Register Name	After Reset	Remarks
0007Ah				
0007Bh				
0007Ch				
0007Dh				
0007Eh				
0007Fh				
00080h	U0MR_0	UART0_0 Transmit/Receive Mode Register	00h	
00081h	U0BRG_0	UART0_0 Bit Rate Register	XXh	
00082h	U0TB_0	UART0_0 Transmit Buffer Register	XXh	
00083h			XXh	
00084h	U0C0_0	UART0_0 Transmit/Receive Control Register 0	00001000b	
00085h	U0C1_0	UART0_0 Transmit/Receive Control Register 1	00000010b	
00086h	U0RB_0	UART0_0 Receive Buffer Register	XXXXh	
00087h				
00088h	U0IR_0	UART0_0 Interrupt Flag and Enable Register	00h	
00089h				
0008Ah				
0008Bh				
0008Ch	LINCR2_0	LIN_0 Special Function Register	00h	
0008Dh				
0008Eh	LINCT_0	LIN_0 Control Register	00h	
0008Fh	LINST_0	LIN_0 Status Register	00h	
00090h	U0MR_1	UART0_1 Transmit/Receive Mode Register	00h	
00091h	U0BRG_1	UART0_1 Bit Rate Register	XXh	
00092h	U0TB_1	UART0_1 Transmit Buffer Register	XXh	
00093h			XXh	
00094h	U0C0_1	UART0_1 Transmit/Receive Control Register 0	00001000b	
00095h	U0C1_1	UART0_1 Transmit/Receive Control Register 1	00000010b	
00096h	U0RB_1	UART0_1 Receive Buffer Register	XXXXh	
00097h				
00098h	U0IR_1	UART0_1 Interrupt Flag and Enable Register	00h	
00099h				
0009Ah				
0009Bh				
0009Ch				
0009Dh				
0009Eh				
0009Fh				
000A0h				
000A1h				
000A2h				
000A3h				
000A4h				
000A5h				
000A8h				
000A9h				
000AAh				
000ABh				
000ACh				
000ADh				
000AEh				
000AFh				
000B0h				
000B1h				
000B4h				
000B5h				
000B8h				
000B9h				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.4 SFR Information (4) (1)

Address	Symbol	Register Name	After Reset	Remarks
000BAh				
000BBh				
000BCh				
000BDh				
000BEh				
000BFh				
000C0h	U2MR	UART2 Transmit/Receive Mode Register	00h	
000C1h	U2BRG	UART2 Bit Rate Register	00h	
000C2h	U2TB	UART2 Transmit Buffer Register	00h	
000C3h			00h	
000C4h	U2C0	UART2 Transmit/Receive Control Register 0	00001000b	
000C5h	U2C1	UART2 Transmit/Receive Control Register 1	00000010b	
000C6h	U2RB	UART2 Receive Buffer Register	0000h	
000C7h				
000C8h	U2RXDF	UART2 Digital Filter Function Select Register	00h	
000C9h				
000CAh				
000CBh				
000CCh				
000CDh				
000CEh				
000CFh				
000D0h	U2SMR5	UART2 Special Mode Register 5	00h	
000D1h				
000D2h				
000D3h				
000D4h	U2SMR4	UART2 Special Mode Register 4	00h	
000D5h	U2SMR3	UART2 Special Mode Register 3	00h	
000D6h	U2SMR2	UART2 Special Mode Register 2	00h	
000D7h	U2SMR	UART2 Special Mode Register	00h	
000D8h				
000D9h				
000DAh				
000DBh				
000DCh				
000DDh				
000DEh				
000DFh				
000E0h	IICCR_0	I^2C_0 Control Register	00001110b	
000E1h	SSBR_0	SS_0 Bit Counter Register	11111000b	
000E2h	SITDR_0	SI_0 Transmit Data Register	FFh	
000E3h			FFh	
000E4h	SIRDR_0	SI_0 Receive Data Register	FFh	
000E5h			FFh	
000E6h	SICR1_0	SI_0 Control Register 1	00h	
000E7h	SICR2_0	SI_0 Control Register 2	01111101b	
000E8h	SIMR1_0	SI_0 Mode Register 1	00010000b	
000E9h	SIER_0	SI_0 Interrupt Enable Register	00h	
000EAh	SISR_0	SI_0 Status Register	00h	
000EBh	SIMR2_0	SI_0 Mode Register 2	00h	
000ECh				
000EDh				
000EEh				
000EFh				
000F0h				
000F1h				
000F2h				
000F3h				
000F4h				
000F5h				
000F6h				
000F7h				
000F8h				
000F9h				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.6 SFR Information (6) (1)

Address	Symbol	Register Name	After Reset	Remarks
0013Ah	TRCGRA_0	Timer RC_0 General Register A	FFFFh	
0013Bh				
0013Ch	TRCGRB_0	Timer RC_0 General Register B	FFFFh	
0013Dh				
0013Eh	TRCGRC_0	Timer RC_0 General Register C	FFFFh	
0013Fh				
00140h	TRCGRD_0	Timer RC_0 General Register D	FFFFh	
00141h				
00142h	TRCMR_0	Timer RC_0 Mode Register	01001000b	
00143h	TRCCR1_0	Timer RC_0 Control Register 1	00h	
00144h	TRCIER_0	Timer RC_0 Interrupt Enable Register	01110000b	
00145h	TRCSR_0	Timer RC_0 Status Register	01110000b	
00146h	TRCIOR0_0	Timer RC_0 I/O Control Register 0	10001000b	
00147h	TRCIOR1_0	Timer RC_0 I/O Control Register 1	10001000b	
00148h	TRCCR2_0	Timer RC_0 Control Register 2	00011000b	
00149h	TRCDF_0	Timer RC_0 Digital Filter Function Select Register	00h	
0014Ah	TRCOER_0	Timer RC_0 Output Enable Register	01111111b	
0014Bh	TRCADCR_0	Timer RC_0 A/D Conversion Trigger Control Register	11110000b	
0014Ch	TRCOPR_0	Timer RC_0 Output Waveform Manipulation Register	00h	
0014Dh	TRCELCCR_0	Timer RC_0 ELC Cooperation Control Register	00h	
0014Eh				
0014Fh				
00150h				
00151h				
00152h				
00153h				
00154h				
00155h				
00156h				
00157h				
00158h				
00159h				
0015Ah				
0015Bh				
0015Ch				
0015Dh				
0015Eh				
0015Fh				
00160h				
00161h				
00162h				
00163h				
00164h				
00165h				
00166h				
00167h				
00168h				
00169h				
0016Ah				
0016Bh				
0016Ch				
0016Dh				
0016Eh				
0016Fh				
00170h	TRESEC	Timer RE2 Counter Data Register Timer RE2 Second Data Register	00h	
00171h	TREMIN	Timer RE2 Compare Data Register Timer RE2 Minute Data Register	00h	
00172h	TREHR	Timer RE2 Hour Data Register	00h	
00173h	TREWK	Timer RE2 Day-of-the-Week Data Register	00h	
00174h	TREDY	Timer RE2 Day Data Register	00000001b	
00175h	TREMON	Timer RE2 Month Data Register	00000001b	
00176h	TREYR	Timer RE2 Year Data Register	00h	
00177h	TRECR	Timer RE2 Control Register	00000100b	
00178h	TRECSR	Timer RE2 Count Source Select Register	00001000b	
00179h	TREADJ	Timer RE2 Clock Error Correction Register	00h	

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.8 SFR Information (8) (1)

Address	Symbol	Register Name	After Reset	Remarks
0023Ah	MSTCR2	Module Standby Control Register 2	00h	
0023Bh	MSTCR3	Module Standby Control Register 3	00h	
0023Ch	MSTCR4	Module Standby Control Register 4	00h	
0023Dh				
0023Eh				
0023Fh				
00240h				
00241h				
00242h				
00243h				
00244h				
00245h				
00246h				
00247h				
00248h				
00249h				
0024Ah				
0024Bh				
0024Ch				
0024Dh				
0024Eh				
0024Fh				
00250h				
00251h				
00252h	FST	Flash Memory Status Register	10000X00b	
00253h				
00254h	FMR0	Flash Memory Control Register 0	00h	
00255h	FMR1	Flash Memory Control Register 1	00h	
00256h	FMR2	Flash Memory Control Register 2	00h	
00257h				
00258h				
00259h				
0025Ah				
0025Bh				
0025Ch				
0025Dh				
0025Eh				
0025Fh				
00260h	AIADR0L	Address Match Interrupt Address 0L Register	XXXXh	
00261h				
00262h	AIADR0H	Address Match Interrupt Address 0H Register	0000XXXXb	
00263h	AIEN0	Address Match Interrupt Enable 0 Register	00h	
00264h	AIADR1L	Address Match Interrupt Address 1L Register	XXXXh	
00265h				
00266h	AIADR1H	Address Match Interrupt Address 1H Register	0000XXXXb	
00267h	AIEN1	Address Match Interrupt Enable 1 Register	00h	
00268h				
00269h				
0026Ah				
0026Bh				
0026Ch				
0026Dh				
0026Eh				
0026Fh				
00270h				
00271h				
00272h				
00273h				
00274h				
00275h				
00276h				
00277h				
00278h				
00279h				
0027Ah				
0027Bh				
0027Ch				
0027Dh				
0027Eh				
0027Fh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.9 SFR Information (9) (1)

Address	Symbol	Register Name	After Reset	Remarks
00280h	DTCTL	DTC Activation Control Register	00h	
00281h				
00282h				
00283h				
00284h				
00285h				
00286h				
00287h				
00288h	DTCEN0	DTC Activation Enable Register 0	00h	
00289h	DTCEN1	DTC Activation Enable Register 1	00h	
0028Ah	DTCEN2	DTC Activation Enable Register 2	00h	
0028Bh	DTCEN3	DTC Activation Enable Register 3	00h	
0028Ch				
0028Dh	DTCEN5	DTC Activation Enable Register 5	00h	
0028Eh	DTCEN6	DTC Activation Enable Register 6	00h	
0028Fh				
00290h	CRCSAR	SFR Snoop Address Register	0000h	
00291h				
00292h	CRCMR	CRC Control Register	00h	
00293h				
00294h	CRCD	CRC Data Register	0000h	
00295h				
00296h	CRCIN	CRC Input Register	00h	
00297h				
00298h				
00299h				
0029Ah				
0029Bh				
0029Ch				
0029Dh				
0029Eh				
0029Fh				
002A0h	TRJ_0SR	Timer RJ_0 Pin Select Register	08h	
002A1h				
002A2h				
002A3h				
002A4h				
002A5h	TRCCLKSR	Timer RCCLK Pin Select Register	00h	
002A6h	TRC_0SR0	Timer RC_0 Pin Select Register 0	00h	
002A7h	TRC_0SR1	Timer RC_0 Pin Select Register 1	00h	
002A8h				
002A9h				
002AAh				
002ABh				
002ACh				
002ADh	TIMSR	Timer Pin Select Register	00h	
002AEh	U_0SR	UART0_0 Pin Select Register	00h	
002AFh	U_1SR	UART0_1 Pin Select Register	00h	
002B0h				
002B1h				
002B2h	U2SR0	UART2 Pin Select Register 0	00h	
002B3h	U2SR1	UART2 Pin Select Register 1	00h	
002B4h				
002B5h				
002B6h	INTSR0	INT Interrupt Input Pin Select Register 0	00h	
002B7h				
002B8h				
002B9h	PINSR	I/O Function Pin Select Register	00h	
002BAh				
002BBh				
002BCh				
002BDh				
002BEh	PMCSEL	Pin Assignment Select Register	00h	
002BFh				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.12 SFR Information (12) (1)

Address	Symbol	Register Name	After Reset	Remarks
06B00h	TSCUCR0	TSCU Control Register 0	0000h	
06B01h				
06B02h	TSCUCR1	TSCU Control Register 1	0000000000010000b	
06B03h				
06B04h	TSCUMR	TSCU Mode Register	0000000010000000b	
06B05h				
06B06h	TSCUTCR0A	TSCU Timing Control Register 0A	0000000001111111b	
06B07h				
06B08h	TSCUTCR0B	TSCU Timing Control Register 0B	0000000001111111b	
06B09h				
06B0Ah	TSCUTCR1	TSCU Timing Control Register 1	0000000000000001b	
06B0Bh				
06B0Ch	TSCUTCR2	TSCU Timing Control Register 2	0000h	
06B0Dh				
06B0Eh	TSCUTCR3	TSCU Timing Control Register 3	0000h	
06B0Fh				
06B10h	TSCUCHC	TSCU Channel Control Register	0011111100000000b	
06B11h				
06B12h	TSCUFR	TSCU Flag Register	0000h	
06B13h				
06B14h	TSCUSTC	TSCU Status Counter Register	0000h	
06B15h				
06B16h	TSCUSCS	TSCU Secondary Counter Set Register	0000000000100000b	
06B17h				
06B18h	TSCUSCC	TSCU Secondary Counter	0000000000100000b	
06B19h				
06B1Ah	TSCUDBR	TSCU Data Buffer Register	0000h	
06B1Bh				
06B1Ch	TSCUPRC	TSCU Primary Counter	0000h	
06B1Dh				
06B1Eh	TSCURVR0	TSCU Random Value Store Register 0	0000h	
06B1Fh				
06B20h	TSCURVR1	TSCU Random Value Store Register 1	0000h	
06B21h				
06B22h	TSCURVR2	TSCU Random Value Store Register 2	0000h	
06B23h				
06B24h	TSCURVR3	TSCU Random Value Store Register 3	0000h	
06B25h				
06B26h	TSIE0	TSCU Input Enable Register 0	0000h	
06B27h				
06B28h	TSIE1	TSCU Input Enable Register 1	0000h	
06B29h				
06B2Ah	TSIE2	TSCU Input Enable Register 2	0000h	
06B2Bh				
06B2Ch	TSCHSEL0	TSCUCHXA Select Register 0	0000h	
06B2Dh				
06B2Eh	TSCHSEL1	TSCUCHXA Select Register 1	0000h	
06B2Fh				
06B30h	TSCHSEL2	TSCUCHXA Select Register 2	0000h	
06B31h				
06B32h to 06BFFh				
06C00h		Area for storing DTC transfer vector 0	XXh	
06C01h		Area for storing DTC transfer vector 1	XXh	
06C02h		Area for storing DTC transfer vector 2	XXh	
06C03h		Area for storing DTC transfer vector 3	XXh	
06C04h		Area for storing DTC transfer vector 4	XXh	
06C05h				
06C06h				
06C07h				
06C08h		Area for storing DTC transfer vector 8	XXh	
06C09h		Area for storing DTC transfer vector 9	XXh	

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

4. Electrical Characteristics

4.1 Absolute Maximum Ratings

Table 4.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
Vcc/AVcc ICEVcc	Supply voltage		–0.3 to 6.5	V
V_I	Input voltage		–0.3 to Vcc + 0.3	V
V_O	Output voltage		–0.3 to Vcc + 0.3	V
P_d	Power dissipation	–40°C ≤ Topr ≤ 85°C	500	mW
T_{opr}	Operating ambient temperature		–20 to 85 (N version)/ –40 to 85 (D version)	°C
T_{stg}	Storage temperature		–65 to 150	°C

4.3 Peripheral Function Characteristics

Table 4.3 A/D Converter Characteristics
(Vcc/AVcc = Vref = 2.2 V to 5.5 V, Vss = 0 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
—	Resolution		V_{ref} = AVcc		—	—	10	Bit
—	Absolute accuracy	10-bit mode	V_{ref} = AVcc = 5.0 V	AN0 to AN19 input	—	—	±3	LSB
			V_{ref} = AVcc = 3.3 V	AN0 to AN19 input	—	—	±5	LSB
			V_{ref} = AVcc = 3.0 V	AN0 to AN19 input	—	—	±5	LSB
			V_{ref} = AVcc = 2.2 V	AN0 to AN19 input	—	—	±5	LSB
		8-bit mode	V_{ref} = AVcc = 5.0 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AVcc = 3.3 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AVcc = 3.0 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AVcc = 2.2 V	AN0 to AN19 input	—	—	±2	LSB
ϕAD	A/D conversion clock		4.0 V ≤ V_{ref} = AVcc ≤ 5.5 V (1)		2	—	20	MHz
			3.2 V ≤ V_{ref} = AVcc ≤ 5.5 V (1)		2	—	16	MHz
			2.7 V ≤ V_{ref} = AVcc ≤ 5.5 V (1)		2	—	10	MHz
			2.2 V ≤ V_{ref} = AVcc ≤ 5.5 V (1)		2	—	5	MHz
—	Tolerance level impedance				—	3	—	kΩ
I_{vref}	Vref current		Vcc = 5 V, XIN = f1 = fAD = 20 MHz		—	45	—	µA
t_{CONV}	Conversion time	10-bit mode	V_{ref} = AVcc = 5.0 V, ϕAD = 20 MHz		2.2	—	—	µs
		8-bit mode	V_{ref} = AVcc = 5.0 V, ϕAD = 20 MHz		2.2	—	—	µs
t_{SAMP}	Sampling time		ϕAD = 20 MHz		0.8	—	—	µs
V_{ref}	Reference voltage				2.2	—	AVcc	V
V_{IA}	Analog input voltage (2)				0	—	V_{ref}	V
OCVREF	On-chip reference voltage		2MHz ≤ ϕAD ≤ 4MHz		1.19	1.34	1.49	V

Notes:
1. If the CPU and the flash memory stop, the A/D conversion result will be undefined.
2. When the analog input voltage exceeds the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 4.4 Comparator B Characteristics
(Vcc/AVcc = 2.2 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{ref}	IVREF1, IVREF3 input reference voltage		0	—	Vcc – 1.4	V
V_I	IVCMP1, IVCMP3 input voltage		–0.3	—	Vcc + 0.3	V
—	Offset		—	5	100	mV
t_d	Comparator output delay time (1)	V_I = V_{ref} ±100 mV	—	0.1	—	µs
I_{CMP}	Comparator operating current	Vcc = 5.0 V	—	17.5	—	µA

Note:
1. When the digital filter is not selected.

Table 4.5 Flash Memory (Program ROM) Characteristics (Vcc = 2.7 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		1,000 (2)	—	—	times
—	Byte program time (Program and erase endurance ≤ 100 times)		—	—	—	µs
—	Byte program time (Program and erase endurance ≤ 1,000 times)		—	—	—	µs
—	Word program time (Program and erase endurance ≤ 100 times)	Topr = 25°C, Vcc = 5.0 V	—	100	200	µs
—	Word program time (Program and erase endurance ≤ 100 times)		—	100	400	µs
—	Word program time (Program and erase endurance ≤ 1,000 times)		—	100	650	µs
—	Block erase time		—	0.3	4	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		–20 (N ver.) –40 (D ver.)	—	85	°C
—	Data hold time (6)	Ambient temperature = 55°C (7)	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 100 or 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. The data hold time includes 7,000 hours under an environment of ambient temperature 85°C.

Table 4.8 Voltage Detection 1 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level Vdet1_0 (1)	When Vcc falls	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 (1)	When Vcc falls	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 (1)	When Vcc falls	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 (1)	When Vcc falls	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 (1)	When Vcc falls	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 (1)	When Vcc falls	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 (1)	When Vcc falls	2.80	3.10	3.40	V
	Voltage detection level Vdet1_7 (1)	When Vcc falls	2.95	3.25	3.55	V
	Voltage detection level Vdet1_8 (1)	When Vcc falls	3.10	3.40	3.70	V
	Voltage detection level Vdet1_9 (1)	When Vcc falls	3.25	3.55	3.85	V
	Voltage detection level Vdet1_A (1)	When Vcc falls	3.40	3.70	4.00	V
	Voltage detection level Vdet1_B (1)	When Vcc falls	3.55	3.85	4.15	V
	Voltage detection level Vdet1_C (1)	When Vcc falls	3.70	4.00	4.30	V
	Voltage detection level Vdet1_D (1)	When Vcc falls	3.85	4.15	4.45	V
	Voltage detection level Vdet1_E (1)	When Vcc falls	4.00	4.30	4.60	V
	Voltage detection level Vdet1_F (1)	When Vcc falls	4.15	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet1 – 0.1) V	—	60	150	µs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 4.9 Voltage Detection 2 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0	When Vcc falls	3.70	4.00	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		—	0.1	—	µs
—	Voltage detection 2 circuit response time (1)	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	µs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (2)		—	—	100	µs

Notes:
1. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 4.16 DC Characteristics (3) [2.7 V ≤ Vcc < 4.2 V] (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –5 mA	Vcc – 0.5	—	Vcc	V
			Drive capacity is low	I_{OH} = –1 mA	Vcc – 0.5	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL} = 5 mA	—	—	0.5	V
			Drive capacity is low	I_{OL} = 1 mA	—	—	0.5	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, RXD_0, RXD_1, $\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\underline{SCL\_0}$, SDA_0, SSI_0, $\overline{SCS\_0}$, SSCK_0, SSO_0			0.1	0.4	—	V
		$\overline{RESET}$	Vcc = 3.0 V		0.1	0.5	—	V
I_{IH}	Input high current		V_I = 3.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		42	84	168	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.19 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—		—	2.2	—	mA
			5 MHz	Off	Off	125 kHz	Divide-by-8	—		—	0.8	—	mA
		High-speed on-chip oscillator mode	Off	Off	5 MHz (3)	125 kHz	No division	—		—	2.5	10	mA
			Off	Off	5 MHz (3)	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	300	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0		—	80	350	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 1.8 V to 2.7 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

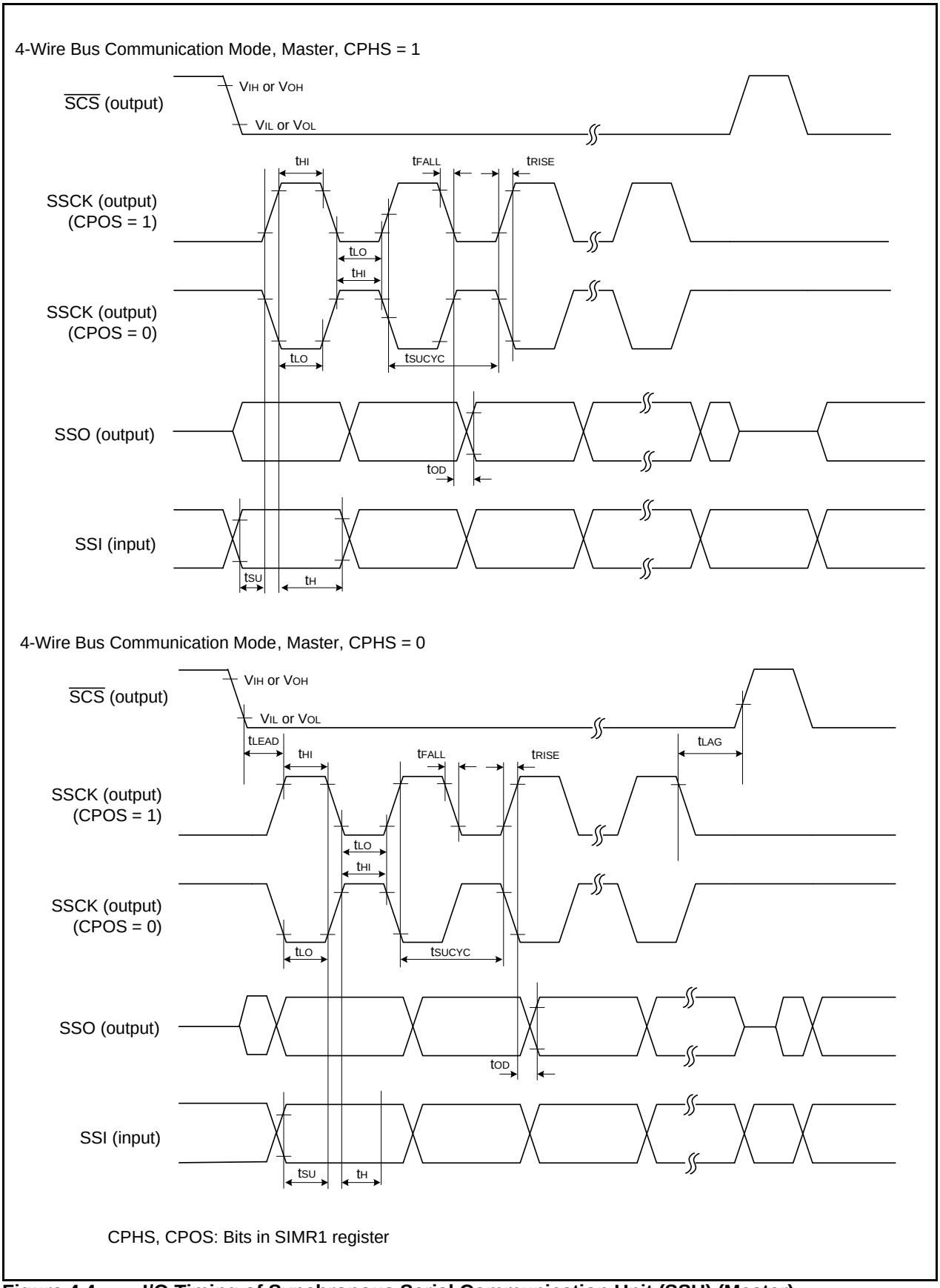


Figure 4.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

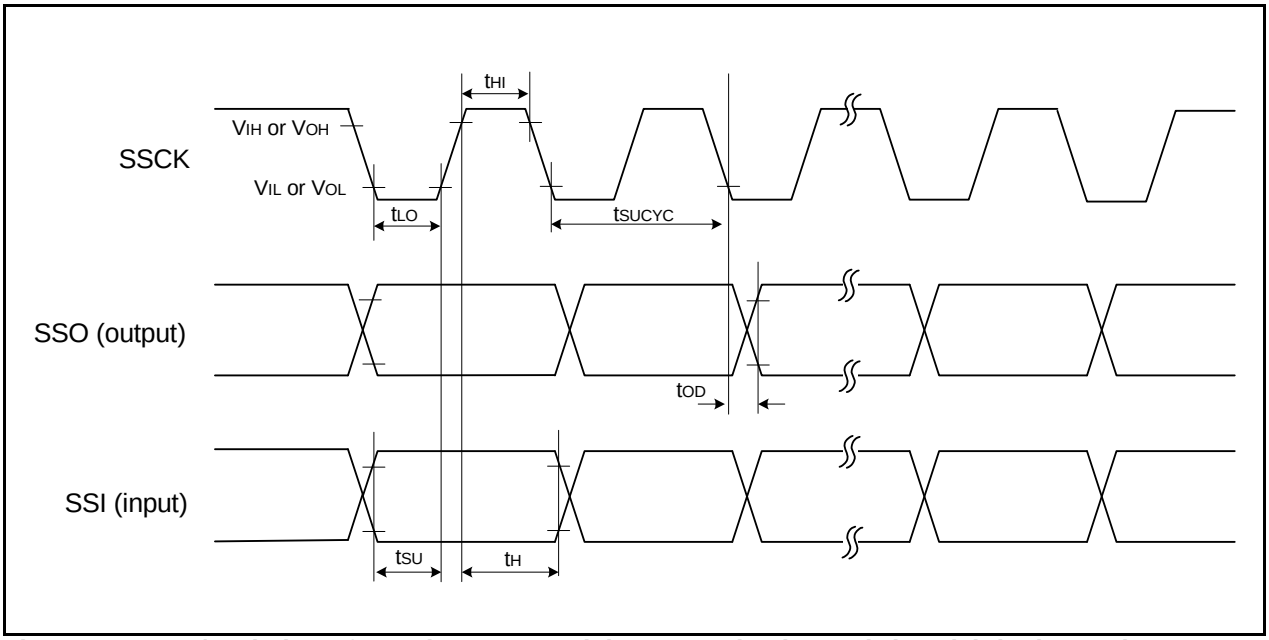


Figure 4.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

Table 4.24 Timing Requirements of Serial Interface (Internal clock selected as transfer clock (master communication))

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{d(C-Q)}$	TXDi output delay time	—	200	—	30	—	10	ns
$t_{su(D-C)}$	RXDi input setup time (1)	150	—	120	—	90	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	90	—	90	—	ns

i = 0 or 1

Note:

1. External pin load condition CL = 30 pF

Table 4.25 Timing Requirements of Serial Interface (External clock selected as transfer clock (slave communication))

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	300	—	200	—	ns
$t_{w(CKH)}$	CLKi input high width	400	—	150	—	100	—	ns
$t_{w(CKL)}$	CLKi input low width	400	—	150	—	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	—	120	—	90	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	30	—	10	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	90	—	90	—	ns

i = 0 or 1

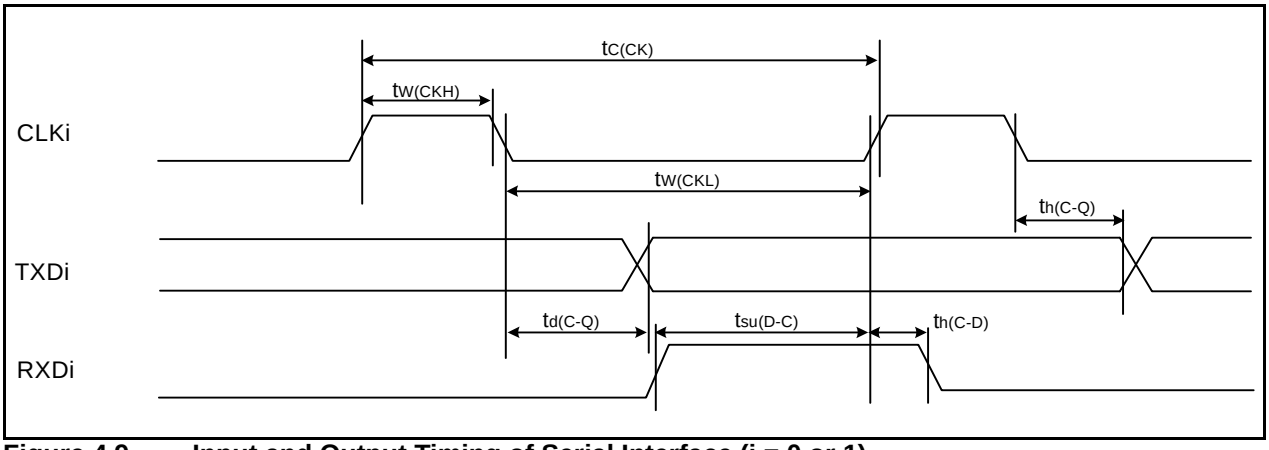


Figure 4.9 Input and Output Timing of Serial Interface (i = 0 or 1)

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.